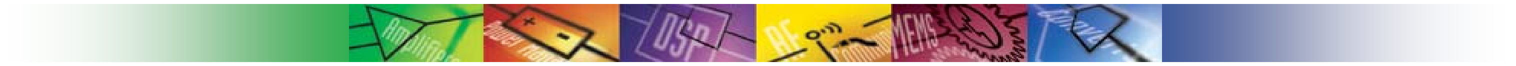

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	4 X 4 X 0.85 (1.8 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS000522E

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.18E-02	86.91	869100	31.88	318762
Thermosets	Epoxy & Phenol Resin	Proprietary	1.73E-03	12.78	127800	4.69	46874
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.31	3100	0.11	1137
Subtotal			1.35 E-02	100.00	1000000	36.68	366773

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.88 E-02	97.50	975000	51.00	510044
Copper & its alloys	Iron	7439-89-6	4.54 E-04	2.35	23500	1.23	12293
Copper & its alloys	Zinc	7440-66-6	2.32 E-05	0.12	1200	0.06	628
Copper & its alloys	Phosphorus	7723-14-0	5.79 E-06	0.03	300	0.02	157
Subtotal			1.93 E-02	100.00	1000000	52.31	523122

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.97 E-04	100.0	1000000	1.08	10766

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.69 E-04	100.0	1000000	1.54	15415

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.25 E-04	100.0	1000000	0.88	8808

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	2.17 E-03	100.0	1000000	5.87	58723

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.70 E-04	77.71	777100	1.27	12739
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Butyrolactone, gamma-	96-48-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Organosilane	TS ref# 10001	1.88 E-05	3.11	31100	0.05	510
Other inorganic materials	Copper(II) oxide	1317-38-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.15 E-06	0.52	5200	0.009	85
Subtotal			6.05 E-04	100.0	1000000	1.64	16393

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary